

View Online at <https://aerobasegroup.com/nsn/8040-01-121-3868>

**Physical Form:**

Paste

**Specific Usage Design:**

For bonding semiconductors and other electronic components to chassis or heat sinks

**Features Provided:**

Separate catalyst

**Special Features:**

Thermally conductive

**Color:**

Natural

**Material:**

Plastic epoxy

**Shelf Life:**

N/a

**Unit Of Measure:**

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**Demilitarization:**

No

**Fiig:**

A535p0